

True Multi-Touch Capacitive Touch Panel Controller

INTRODUCTION

The FT5X26 is single-chip capacitive touch panel controllers with built-in enhanced Micro-controller unit (MCU). It provides the benefits of full screen common mode scan technology, fast response time and high level of accuracy. It can drive capacitive type touch panel with up to 42 driving and 30 sensing lines.

FEATURES

- Mutual Capacitive Sensing Techniques
- Full Screen Common Mode Scan Techniques
- True Multi-touch up to 10 Points of absolute X and Y Coordinates
- High immunity to RF and power Interferences
- 5626NEm Supports up to 40TX + 27 RX
- 5726NEi Supports up to 42TX + 30 RX
- Full Programmable Scan Sequences to Support Various TX/RX Configurations
- High Report Rate: Over 100Hz
- Touch Resolution of 325 Dots per Inch (dpi) or above
- Auto-calibration
- Support Interfaces:I2C

- Built-in 64KB Flash
- 2.7 to 3.6V Operating Voltage
- IOVCC (Ext. or Int.) supports from 1.8V to 3.6V
- Single Channel(TX/RX)resistance: Up to 100K Ω
- Single Channel (transmit/receive) Capacitance: 40pF
- Optimal Sensing Mutual Capacitance: 0.5pF~4pF
- 12-Bit ADC Accuracy
- 3 Operating Modes
 - Active
 - Monitor
 - Hibernation
- Operating Temperature Range: -40°C to +85°C
- Package:
 - > QFN88L 10x10x0.8mm, 0.4mm/pitch

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1 OVERVIEW

1.1 Typical Applications

FT5X26 accommodates a wide range of applications with a set of buttons up to a 2D touch sensing device; their typical applications are listed below.

- Tablet
- Navigation systems, GPS
- Game consoles
- POS (Point of Sales) devices

FT5X26 support Touch Panel, the spec is listed in the following table,

Part Number	Package	тх	RX	Total Channels	Recommended for Smart Phone TP Size (16:9)
FT5626NEm	QFN 88L 10x10x0.8mm Pitch =0.4mm	40	27	67	\leq 10.1", Sensor Pitch:6mm
FT5726NEi	QFN 88L 10x10x0.8mm Pitch =0.4mm	42	30	72	≦11.6", Sensor Pitch:6mm

2 FUNCTIONAL DESCRIPTION

2.1 Architectural Overview

Figure 2-1 shows the overall architecture for the FT5X26.

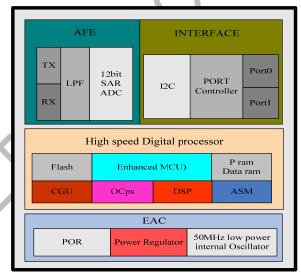


Figure 2-1 System Architecture Diagram

The FT5X26 is comprised of five main functional parts listed below,

Touch Panel Interface Circuits

The main function for the AFE and AFE controller is to interface with the touch panel. It scans the panel by sending AC signals to the panel and processes the received signals from the panel. It includes both Transmit (TX) and Receive (RX) functions. Key parameters to configure this circuit can be sent via serial interfaces.

• Enhanced MCU with DSP accelerator

For the Enhanced MCU, larger program and data memories are supported. Furthermore, a Flash memory is implemented to store programs and some key parameters.

Complex signal processing algorithms are implemented by MCU and DSP accelerator to detect the touches reliably and efficiently. Communication protocol software is also implemented in this MCU to exchange data and control information with the host processor.

- External Interface
 - > I2C: an interface for data exchange with host
 - > INT: an interrupt signal to inform the host processor that touch data is ready for read
 - > RSTN: an external low signal reset the chip. The port is also use to wake up the FT5X26 from the Hibernate mode.
- A watch dog timer is implemented to ensure the robustness of the chip.
- A voltage regulator to generate 1.8V for digital circuits from the input VDD3 supply
- Power On Reset (POR) is active until VDDD is higher than some level and hold decades of µs

2.2 MCU

This section describes some critical features and operations supported by the enhanced MCU.

Figure 2-2 shows the overall structure of the MCU block. In addition to the enhanced MCU core, we have added the following circuits,

- A DSP accelerator cooperates with MCU to process the complex algorithms
- Timer: A number of timers are available to generate different clocks.
- Clock Manager: To control various clocks under different operation conditions of the system

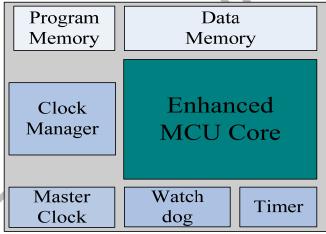


Figure 2-2 MCU Block Diagram

2.3 Operation Modes

FT5X26 offers following three modes:

Active Mode

When in this mode, FT5X26 actively scans the panel. The default scan rate is 100 frames per second. The host processor can configure it to speed up or to slow down.

Monitor Mode

In this mode, FT5X26 scans the panel at a reduced speed. The default scan rate is 25 frames per second and the host processor can increase or decrease this rate. In this mode, most algorithms are stopped. A simpler algorithm is being executed to determine if there is a touch or not. When a touch is detected, FT5X26 shall enter the Active mode immediately to acquire the touch information quickly. During this mode, the serial port is closed and no data shall be transferred with the host processor.

Hibernate Mode

In this mode, the chip is set in a power down mode. It shall only respond to the "RESET" signal from the host processor. The chip therefore consumes very little current, which help prolong the standby time for the portable devices.

2.4 Host Interface

Figure 2-3 shows the interface between a host processor and FT5X26. This interface consists of the following three sets of signals:

- Serial Interface
- Interrupt from FT5X26 to the Host
- Reset Signal from the Host to FT5X26

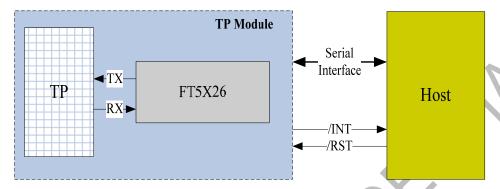


Figure 2-3 Host Interface Diagram

The serial interface of FT5X26 is I2C. The detail of the interface is described in detail in Section 2.5. The interrupt signal (/INT) is used for FT5X26 to inform the host that data are ready for the host to receive. The /RST signal is used for the host to wake up FT5X26 from the Hibernate mode. After resetting, FT5X26 shall enter the Active mode.

2.5 Serial Interface

FT5X26 supports the I2C interfaces, which can be used by a host processor or other devices.

The I2C is always configured in the Slave mode. The data transfer format is shown in Figure 2-4.

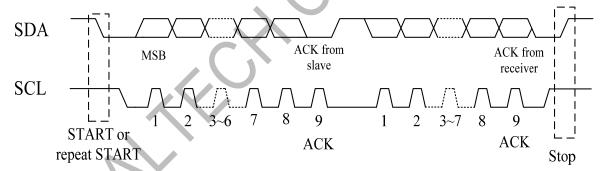


Figure 2-4 I2C Serial Data Transfer Format

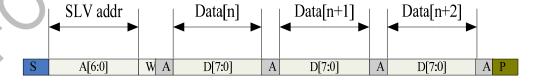


Figure 2-5 I2C master write, slave read

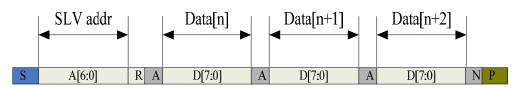


Table 2-1 lists the meanings of the mnemonics used in the above figures.

Table 2-1 Mnemonics Description

Mnemonics	Description				
S	I2C Start or I2C Restart				
A[6:0]	Slave address				
R/ W	READ/WRITE bit, '1' for read, '0'for write				
A(N)	ACK(NACK) bit				
Р	STOP: the indication of the end of a packet (if this bit is missing, S will indicate the end of the current packet and the beginning of the next packet)				

I2C Interface Timing Characteristics is shown in Table 2-2.

Table 2-2 I2C Timing Characteristics

	400	400	
Parameter	Min	Max	Unit
SCL frequency	0	400	KHz
Bus free time between a STOP and START condition	1.3		us
Hold time (repeated) START condition	0.6		us
Data setup time	100		ns
Setup time for a repeated START condition	0.6		us
Setup Time for STOP condition	0.6		us

3 ELECTRICAL SPECIFICATIONS

3.1 Absolute Maximum Ratings

Table 3-1 Absolute Maximum Ratings

Item	Symbol Value		Unit	Note
Power Supply Voltage	VDD3 – VSS	-0.3 ~ +3.6	V	1, 3
I/O Digital Voltage	IOVCC	1.8~3.6	V	1
Operating Temperature	Topr	-40 ~ +85	${\mathfrak C}$	1
Storage Temperature	Tstg	-55 ~ +150	${\mathbb C}$	1

Notes

- 1. If used beyond the absolute maximum ratings, FT5X26 may be permanently damaged. It is strongly recommended that the device be used within the electrical characteristics in normal operations. If exposed to the condition not within the electrical characteristics, it may affect the reliability of the device.
- 2. Make sure VDD (high) ≥VSS (low)

3.2 DC Characteristics

Table 3-2 DC Characteristics

Item	Symbol	Unit	Test Condition	Min.	Тур.	Max.	Note
Input high-level voltage	VIH	V		0.7 x IOVCC		IOVCC	
Input low -level voltage	VIL	V		-0.3	1	0.3 x IOVCC	
Output high -level voltage	VOH	V	IOH=-0.1mA	0.7 x IOVCC			
Output low -level voltage	VOL	٧	IOH=0.1mA			0.3 x IOVCC	
I/O leakage current	ILI	uA	Vin=0~VDD3	-1		1	
Current consumption (Normal operation mode)	lopr	mA	VDD3 = 3V Ta=25℃ MCLK=24MHz				
Current consumption (Monitor mode)	Imon	mA	VDD3 = 3V Ta=25℃ MCLK=24MHz		1	-	
Current consumption (Sleep mode)	Islp	uA	VDD3 = 3V Ta=25℃ MCLK=24MHz	9			
Step-up output voltage	VDD5	V	VDD3= 2.8V				
Step-up output voltage	VDD10	V	VDD3= 2.8V				
Power Supply voltage	VDD3	V		2.7		3.6	

Notes: This sample data is intended for design guidance only. Values shown are typical for a 42Tx × 30Rx sensor configured at 80 Hz report rate. Actual current will depend on the particular sensor design and firmware options.

3.3 AC Characteristics

AC Characteristics of Oscillators

Item	Symbol	Unit	nit Test Condition		Тур.	Max.	Note
OSC clock 1	fosc1	MHz	VDD3 = 2.8V; Ta=25℃	49	50	51	

Table 3-3 AC Characteristics of TX & RX

Item	Symbol	Test Condition	Min	Тур	Max	Unit	Note
TX acceptable clock	ftx		50	150	400	KHz	
TX output rise time	Ttxr			210		nS	
TX output fall time	Ttxf			210		nS	
RX input voltage	Trxi		1.2		1.6	V	

3.4 I/O Ports Circuits

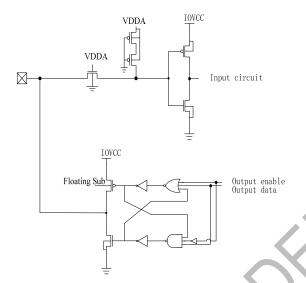


Figure 3-1 General Purpose In/Out Port Circuit.

The input/output property can be configured via firmware setting. The firmware can also control its output behavior as push-pull or as open-drain that SDA of I2C interface is required.

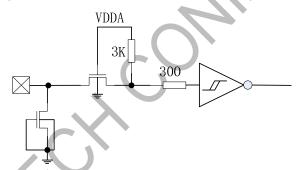


Figure 3-2 Reset Input Port Circuits

3.5 POWER ON/Reset Sequence

Reset should be pulled down to be low before powering on and powering down. I2C shouldn't be used by other devices during Reset time after VDD powering on (Trtp). INT signal will be sent to the host after initializing all parameters and then start to report points to the host. If Power is down, the voltage of supply must be below 0.3V and Tpdt is more than 1ms.

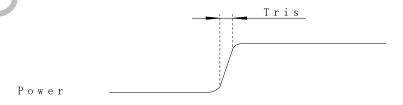


Figure 3-3 Power on time

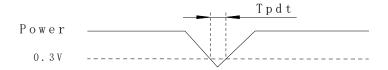


Figure 3-4 Power Cycle requirement

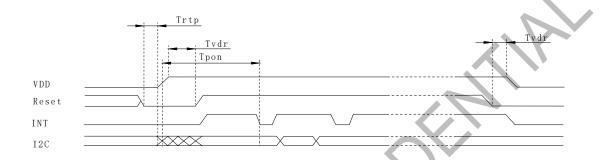


Figure 3-5 Power on Sequence

Reset time must be enough to guarantee reliable reset, the time of starting to report point after resetting approach to the time of starting to report point after powering on.

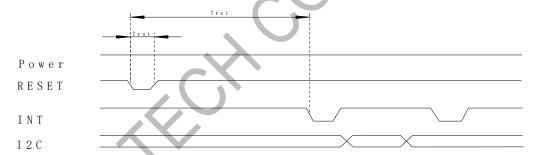


Figure 3-6 Reset Sequence

Table 3-5 Power on/Reset Sequence Parameters

Parameter	Description	Min	Max	Units
Tris	Rise time from 0.1VDD to 0.9VDD		5	ms
Tpdt	Time of the voltage of supply being below 0.3V	5		ms
Trtp	Time of resetting to be low before powering on	100		μS
Tpon	Time of starting to report point after powering on		200	ms
Tvdr	Tvdr Reset time after VDD powering on			ms
Trsi	Trsi Time of starting to report point after resetting		200	ms
Trst	Reset time	1		ms

4 PIN CONFIGURATIONS

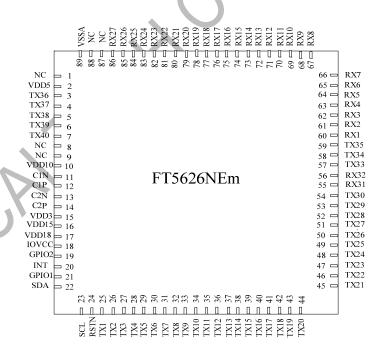
Pin List of FT5X26

Table 4-1 Pin Definition

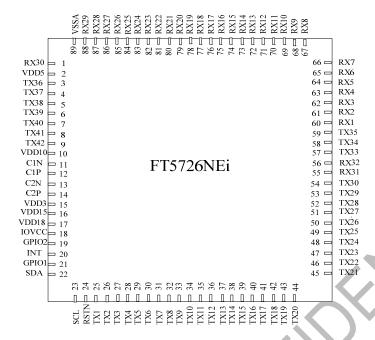
	Pin	Pin No.			
Name	5626NEm	5726NEi	Type	Description	
RX30		1	I	Receiver input pins	
RX29		88	I	Receiver input pins	
RX28		87	I	Receiver input pins	
RX27	86	86	I	Receiver input pins	
RX26	85	85	I	Receiver input pins	
RX25	84	84		Receiver input pins	
RX24	83	83	I	Receiver input pins	
RX23	82	82	I	Receiver input pins	
RX22	81	81	I	Receiver input pins	
RX21	80	80	I	Receiver input pins	
RX20	79	79	I	Receiver input pins	
RX19	78	78	L	Receiver input pins	
RX18	77	77	7	Receiver input pins	
RX17	76	76	The same of the sa	Receiver input pins	
RX16	75	75	1	Receiver input pins	
RX15	74	74		Receiver input pins	
RX14	73	73	ı	Receiver input pins	
RX13	72	72	I	Receiver input pins	
RX12	71	71	ı	Receiver input pins	
RX11	70	70	I	Receiver input pins	
RX10	69	69	ı	Receiver input pins	
RX9	68	68	I	Receiver input pins	
RX8	67	67	I	Receiver input pins	
RX7	66	66	I	Receiver input pins	
RX6	65	65	I	Receiver input pins	
RX5	64	64	I	Receiver input pins	
RX4	63	63	I	Receiver input pins	
RX3	62	62	I	Receiver input pins	
RX2	61	61	I	Receiver input pins	
RX1	60	60	I	Receiver input pins	
TX35	59	59	0	Transmit output pin	
TX34	58	58	0	Transmit output pin	
TX33	57	57	0	Transmit output pin	
TX32	56	56	0	Transmit output pin	
TX31	55	55	0	Transmit output pin	
TX30	54	54	0	Transmit output pin	
TX29	53	53	0	Transmit output pin	
TX28	52	52	0	Transmit output pin	
TX27	51	51	0	Transmit output pin	
L	<u> </u>	<u> </u>	_		

		1		
TX26	50	50	0	Transmit output pin
TX25	49	49	0	Transmit output pin
TX24	48	48	0	Transmit output pin
TX23	47	47	0	Transmit output pin
TX22	46	46	0	Transmit output pin
TX21	45	45	0	Transmit output pin
TX20	44	44	0	Transmit output pin
TX19	43	43	0	Transmit output pin
TX18	42	42	0	Transmit output pin
TX17	41	41	0	Transmit output pin
TX16	40	40	0	Transmit output pin
TX15	39	39	0	Transmit output pin
TX14	38	38	0	Transmit output pin
TX13	37	37	0	Transmit output pin
TX12	36	36	0	Transmit output pin
TX11	35	35	0	Transmit output pin
TX10	34	34	0	Transmit output pin
TX9			0	
	33	33		Transmit output pin
TX8	32	32	0	Transmit output pin
TX7	31	31	0	Transmit output pin
TX6	30	30	0	Transmit output pin
TX5	29	29	0	Transmit output pin
TX4	28	28	0	Transmit output pin
TX3	27	27	0	Transmit output pin
TX2	26	26	0	Transmit output pin
TX1	25	25	0	Transmit output pin
RSTN	24	24	I	External Reset, Low is active
SCL	23	23	I/O	I2C clock input
SDA	22	22	I/O	I2C data input and output
GPIO1	21	21	I/O	General Purpose Input/Output port
INT	20	20	I/O	Interrupt request to the host, or
1141	20	20	1/0	Wakeup request from the host.
GPIO2	19	19	I/O	General Purpose Input/Output port
IOVCC	18	18	PWR	I/O power supply
VDD40	47	47	חאים	digital power supply, A 1µF ceramic
VDD18	17	17	PWR	capacitor to ground is required.
VDD45	40	40	DVVD	digital power supply, A 1µF ceramic
VDD15	16	16	PWR	capacitor to ground is required.
\(\tag{P}\)	4-	4-	D. 4.75	digital power supply, A 1µF ceramic
VDD3	15	15	PWR	capacitor to ground is required.
C2P	14	14		
C2N	13	13		
C1P	12	12		
C1N	11	11		
VDD10	10	10	PWR	digital power supply, A 1µF ceramic
			FVVK	capacitor to ground is required.
NC	9	9	NC	
NC	8	8	NC	

TX40	7	7	0	Transmit output pin
TX39	6	6	0	Transmit output pin
TX38	5	5	0	Transmit output pin
TX37	4	4	0	Transmit output pin
TX36	3	3	0	Transmit output pin
VDD5	2	2	PWR	digital power supply, A 1µF ceramic
VDD3				capacitor to ground is required.
NC	1		NC	
VSS	89	89	PWR	Analog ground
NC	88		NC	. 5
NC	87		NC	7/1



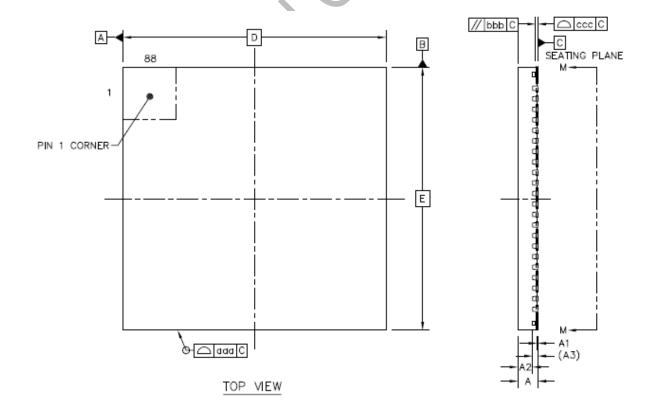
FT5626NEm Package Diagram

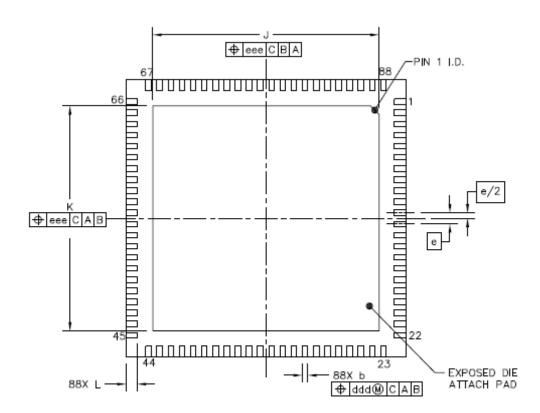


FT5726NEi Package Diagram

5 PACKAGE INFORMATION

5.1 Package Information of QFN-10x10-88L Package





BOTTOM VIEW
VIEW M-M

Item		Symbol	Millimeter		
			Min	Type	Max
Total Thickness		Α	0.7	0.75	8.0
Stand Off		A1	0	0.035	0.05
Mold Thickness		A2		0.55	
L/F Thickness		A3	0.203 REF		
Lead Width		b	0.15	0.2	0.25
Rody Sizo	Χ	D	10 BSC		
Body Size	Υ	E	10 BSC		
Lead Pitch		е	0.4 BSC		
EP Size	Χ	J	8	8.1	8.2
LF Size	Υ	K	8	8.1	8.2
Lead Length		L	0.35	0.4	0.45
Package Edge Tolerance		aaa	0.1		
Mold Flatness		bbb	0.1		
Co Planarity		ccc	0.08		
Lead Offset		ddd	0.1		
Exposed Pad Offset		eee	0.1		

5.2 Order Information

Package Type	QFN
	88Pin(10 * 10)
	88Pin(0.8 - P0.4)
Product Name	FT5X26

Note:

- 1). The last three letters in the product name indicate the package type, lead pitch and thickness and numbers of TX and RX.
- 2). The third last letter indicates the package type . N: QFN-10*10 $\,$
- 3). The second last letter indicates the lead pitch and thickness. E : 0.8 P0.4
- 4). The last letter indicates the numbers of TX and RX. m: 40TX-27RX

i: 42TX-30RX

T: Track Code

F/R:" F" for Lead Free process,

"R" for Halogen Free process

Y: Year Code

WW: Week Code

S: Lot Code

Product Name	Package Type	# TX Pins	# RX Pins
FT5626NEm	QFN-88L	40	27
FT5726NEi	QFN-88L	42	30

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